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**PRIMA-BOND**  
**ME7155**

- Stress Free**
- Solvent Free**
- Thermally Conductive**
- Reworkable**
- Epoxy Paste Adhesive**

**IDEAL FOR:**

- High Power Die Attach**
- Substrate and Component**
- Reworkability**
- Mismatched CTE's**

**DESCRIPTION:**

ME7155 is a reworkable, alumina filled, electrically insulating and thermally conductive epoxy paste adhesive which exhibits outstanding flexibility for bonding materials having highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper). The high thermal conductivity of this material makes it useful for bonding high-powered, large area die and components.

It can be readily reworked at 80-100°C.

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 60 minute )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	750
Glass Transition Temp.(°C)	-25
Current Carrying Capabilities	N/A
Lap-Shear Strength	1000 psi 6.9 N/mm <sup>2</sup>
Device Push-off Strength	1800 psi 12.4 N/mm <sup>2</sup>
Hardness (Type)	80 (A)
Cured Density (gm/cc)	2.3
Thermal Conductivity	12 Btu-in/hr-ft <sup>2</sup> -°F 1.7 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	120
Maximum Continuous Operation Temp. (°C)	150
Avg. Viscosity(0.5 rpm, 24°C) (Brookfield DV-1,spindle CP51)	276,000 cp

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**AVAILABILITY:**

ME7155 is available in syringes for automatic needle dispense applications or in jars.

**CURE SCHEDULES:**

<u>Temperature</u>	<u>Time</u>
80°C	8 hr
100°C	4 hr
125°C	2 hr
150°C	1 hr

**APPLICATION PROCEDURES:**

- ( 1 ) Remove from freezer in original sealed package.
- ( 2 ) Allow to reach room temperature before using.
- ( 3 ) Dispense adhesive onto clean substrate.
- ( 3 ) Cure according to one of the recommended schedules.

**SHELF LIFE:**

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr

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